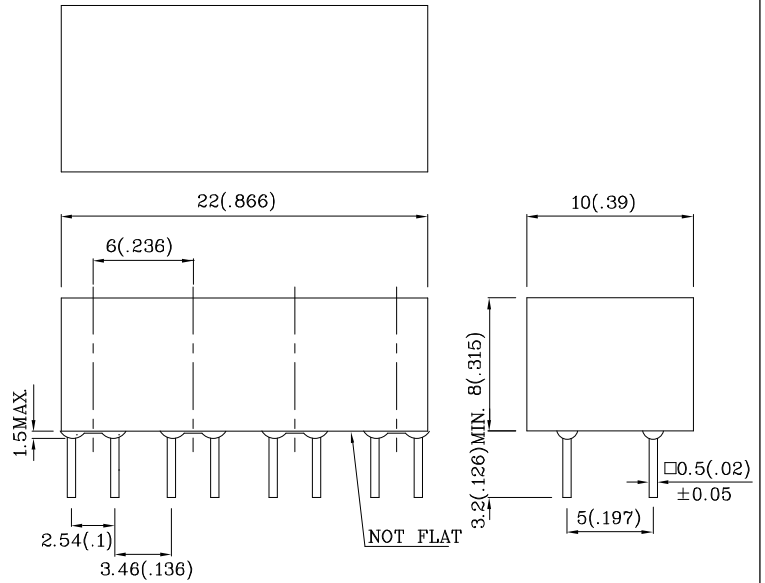


**Features**

- UNIFORM LIGHT EMITTING AREA.
- EASILY MOUNTED ON P.C. BOARDS OR INDUSTRY STANDARD SOCKETS.
- FLUSH MOUNTABLE.
- EXCELLENT ON/OFF CONTRAST.
- CAN BE USED WITH PANELS AND LEGEND MOUNTS.
- MECHANICALLY RUGGED.
- I.C. COMPATIBLE.
- BOTTOM SURFACE OF EPOXY IS NOT FLAT.
- RoHS COMPLIANT.



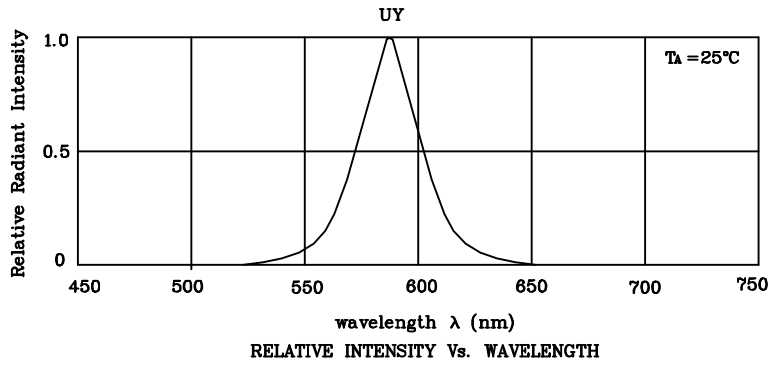
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.25(0.01") unless otherwise noted.
3. Specifications are subject to change without notice.

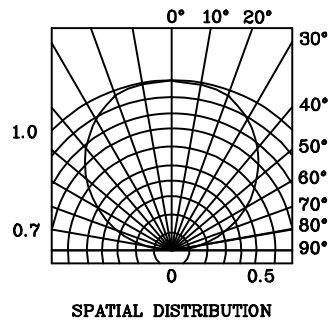
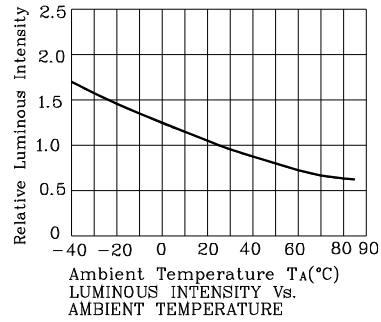
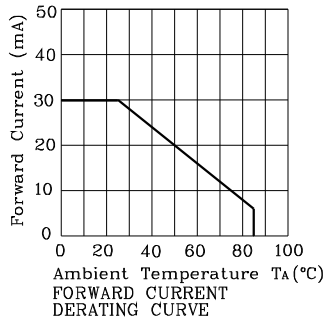
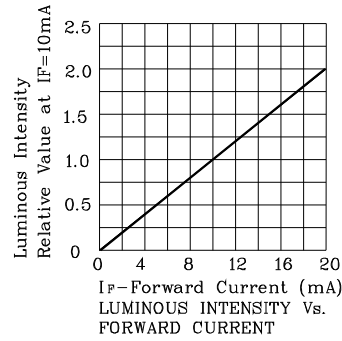
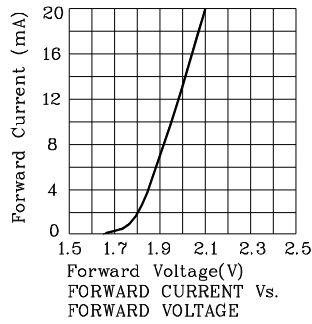
Absolute Maximum Ratings (TA=25°C)		UY (GaAsP/GaP)	Unit
Reverse Voltage	V <sub>R</sub>	5	V
Forward Current	I <sub>F</sub>	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i <sub>FS</sub>	140	mA
Power Dissipation	P <sub>T</sub>	75	mW
Operating Temperature	T <sub>A</sub>	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds		

Operating Characteristics (TA=25°C)		UY (GaAsP/GaP)	Unit
Forward Voltage (Typ.) (I <sub>F</sub> =10mA)	V <sub>F</sub>	1.95	V
Forward Voltage (Max.) (I <sub>F</sub> =10mA)	V <sub>F</sub>	2.5	V
Reverse Current (Max.) (V <sub>R</sub> =5V)	I <sub>R</sub>	10	uA
Wavelength Of Peak Emission (Typ.) (I <sub>F</sub> =10mA)	λ P	590	nm
Wavelength Of Dominant Emission (Typ.) (I <sub>F</sub> =10mA)	λ D	588	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =10mA)	Δλ	35	nm
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	C	20	pF

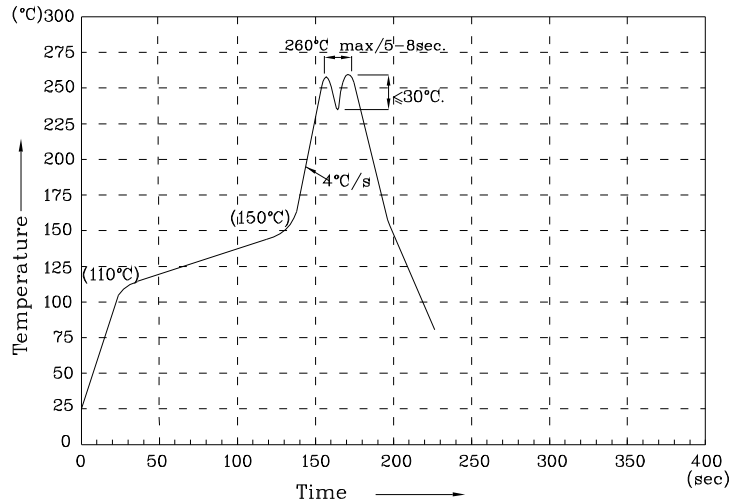
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (I <sub>F</sub> =10mA) mcd		Wavelength nm λ P	Viewing Angle 2 θ 1/2
				min.	typ.	nm	°
XEUY28D	Yellow	GaAsP/GaP	Yellow Diffused	5	9	590	120°
Published Date : JAN.24.,2008      Drawing No : XDSA1954      V4      Checked : B.L.LIU      P.1/4							



❖ UY



Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85 degree°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.

Remarks:

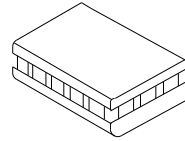
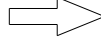
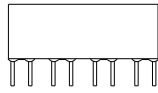
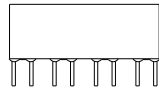
If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous intensity / luminous flux: +/-15%
3. Forward Voltage: +/-0.1V

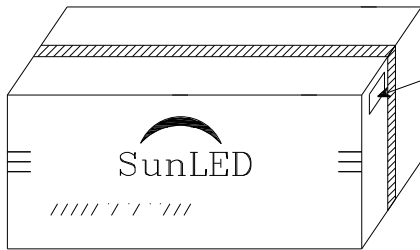
Note: Accuracy may depend on the sorting parameters.

**PACKING & LABEL SPECIFICATIONS**

**XEUY28D**

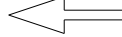


100PCS /BOARD

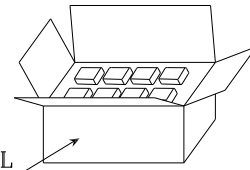


2.4K/BOX

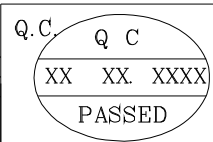
OUTSIDE LABEL




OUTSIDE LABEL



0.3K/BOX



P/NO : XE <sub>xx</sub> 28 <sub>x</sub>	
QTY : 100 pcs	CODE: XXX
S/N : XX	
LOT NO:	
 xxxxxxxxxxxxxxxxxxxxxxxx	
RoHS Compliant	